

ABSTRACT OF THE INVENTION

The present invention relates to a method of packaging a microelectronic device that, in one embodiment, uses a vacuum-assisted underfill process. One embodiment of the method uses a curing process with a tacky film disposed over the device to prevent wicking of the underfill material after the underfill material is in place. One embodiment of the method uses a curing process that utilizes a non-tacky tacky film with a curing process to prevent wicking of the underfill material after the underfill material is in place.

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